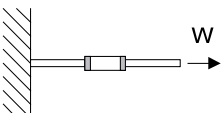
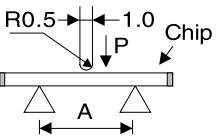


## ■ PERFORMANCE TESTS

TEST	SPECIFICATION	TEST CONDITION		
Solderability	* More than 90% of the terminal electrode will be covered with fresh solder.	* Solder: H63A (Eutectic Solder) * Solder Temperature: $230 \pm 5^{\circ}\text{C}$ * Flux: Rosin		
Soldering Heat Resistance	* The chip will not crack. * More than 75% of the terminal electrode will be covered with solder.	* Solder: H63A (Eutectic Solder) * Solder Temperature: $260 \pm 5^{\circ}\text{C}$ * Flux: Rosin		
Terminal Strength	* The terminal electrode will not break and the ferrite will not be damaged. 	TYPE	KGF	Time(sec)
		MLI-160808	0.6	$30 \pm 5$
		MLI-201209		
		MLI-201212		
		MLI-321611	1.0	
MLI-322513				
Bending Strength	* There will be no mechanical damage. * The ferrite will not be damaged. 	TYPE	A(mm)	KGF
		MLI-160808	1.0	0.6
		MLI-201209	1.4	1.0
		MLI-201212		
		MLI-321611	2.0	2.0
MLI-322513				

## ■ CLIMATIC TESTS

TEST	SPECIFICATION	TEST CONDITION
Thermal Shock (Temperature Cycle)	There shall be no mechanical damage. Inductance shall be within 10% of the initial value.	* Temperature cycles $-40^{\circ}\text{C}$ then $+85^{\circ}\text{C}$ for 30 minutes each. Total Cycles: 100
Humidity Resistance	Q-value shall be within 30% of the initial value.	* Temperature: $60^{\circ}\text{C}$ * Humidity: 95% RH * Time: $1000 \pm 12$ hour
High Temperature Resistance		* Temperature: $85^{\circ}\text{C} \pm 2^{\circ}\text{C}$
Low Temperature Resistance		* Temperature: $-40^{\circ}\text{C} \pm 2^{\circ}\text{C}$

**NOTE:** Operating Temperature Range:  $-40^{\circ}\text{C}$  TO  $+85^{\circ}\text{C}$

Storage Condition : The temperature should be within  $0 \sim 30^{\circ}\text{C}$

and humidity should be less than 75% RH.

The product should be used within 6 months from the time of delivery.